



JPW  
B

IR-256 (2-2817)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Mario Merlin et al.

Date: June 8, 2004

Serial No.: 10/057,399

Group Art Unit: 2827

Filed: January 25, 2002

Examiner: James M.. Mitchell

For: COMPRSSION ASSEMBLED ELECTRONIC PACKAGE HAVING A PLASTIC  
MOLDED INSULATION RING

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

SUBMISSION OF FORMAL DRAWINGS

Sir:

Enclosed herewith please find seven (7) sheets of formal drawings containing Figures  
1 through 7 for the above-identified application.

I hereby certify that this correspondence is being  
deposited with the United States Postal Service as First  
Class Mail in an envelope addressed to: Commissioner  
for Patents, P.O. Box 1450, Alexandria, VA 22313-  
1450, on June 8, 2004

Brendan J. Kennedy

Name of applicant, assignee or  
Registered Representative

Brendan J. Kennedy  
Signature

June 8, 2004

Date of Signature

Respectfully submitted,

Brendan J. Kennedy

Brendan J. Kennedy

Registration No.: 41,890

OSTROLENK, FABER, GERB & SOFFEN, LLP

1180 Avenue of the Americas

New York, New York 10036-8403

Telephone: (212) 382-0700

BJK:gl